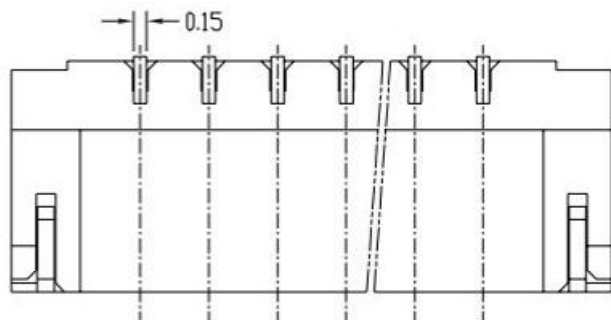


PCB LAYOUT

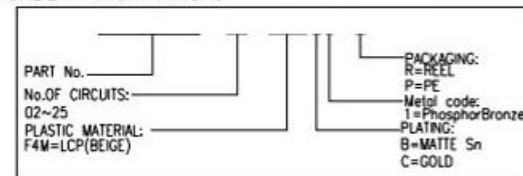


15	11.2	14.2					
14	10.4	13.4					
13	9.6	12.6					
12	8.8	11.8					
11	8.0	11.0	25	19.0	22.0		
10	7.2	10.2	24	18.2	21.2		
9	6.4	9.4	23	17.4	20.4		
8	5.6	8.6	22	16.6	19.6		
7	4.8	7.8	21	15.8	18.8		
6	4.0	7.0	20	15.0	18.0		
5	3.2	6.2	19	14.2	17.2		
4	2.4	5.4	18	13.4	16.4		
3	1.6	4.6	17	12.8	15.8		
2	0.8	3.8	16	12.0	15.0		
孔位	DIM	ADIM	B	孔位	DIM	ADIM	B

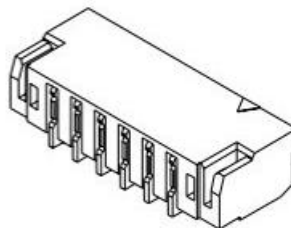
主要技术参数 Main Specifications

- 线数 (Poles): 02 to 25
- 接触电阻 (Contact resistance):  $\leq 20m\Omega$
- 绝缘电阻 (Insulation resistance):  $\geq 100M\Omega$
- 额定电压 (Rated voltage): 30V AC DC
- 额定电流 (Rated current): 0.5A AC DC
- 耐电压 (Withstand Voltage): 200V AC/minute
- 温度范围 (Temperature Range):  $-25^{\circ}C \sim +85^{\circ}C$

ORDER INFORMATION:



C	Solder TAB	2 PCS	PhosphorBronze	Motte Sn-plated
B	CONTACT	n PCS	PhosphorBronze	Motte Sn-plated/GOLD
A	HOUSING	1 PCS	LCP	UL 94V-0, COLOR:BEIGE
ITEM	COMPONENT	Q'TY	MATERIAL	FINISH



X ± 0.3	X' ± 5'
.X ± 0.25	.X' ± 2'
.XX ± 0.20	.XX' ± 1'
.XXX ± 0.10	.XXX' ± 0.5'

UNITS	mm
MAT'L	
FINISH	
Q'TY	PCS

科斯达电子科技有限公司

PART NO.(INTENDED USE) TITLE:  
0.8mm PITCH 90° WAFER SMT TYPE

APPD: DWG NO.:

CHKD: DR: HU 2016.09.28

SCALE	SHEET	REV.
1/1	1/1	A